Cond A7

structure, in contrast to the four-point linkage structure utilized by the prior art. During high-temperature fabrication steps when the substrate is subjected to thermal stresses, the substrate can freely expand toward the corners where no tie bars are provided; and consequently, it can be unwarped by the thermal stresses. This unwarped substrate allows the subsequently implanted ball grid array thereon to have high coplanarity.

Please amend the paragraph on page 6, lines 9-17 as follows:

A8

FIG. 2B is a schematic diagram used to depict the thermal expansion of each substrate 110 during high-temperature fabrication steps. Under the high-temperature conditions, the substrate 110 would normally expand outwards in all directions. However, as illustrated in FIG. 2B, since the upper-left and bottom-left corners of the substrate 110 are provided with the tie bars 131, 132, the thermal expansion would be retarded in these directions; and since no tie bars are provided on the upper-right and bottom-right corners, the substrate 110 can freely expand toward these corners, thus relieving the thermal stresses thereon. As a result, the substrate 110 is unlikely to become warped during the high temperature fabrication steps.

Please amend the paragraph on page 9, lines 6-9 as follows:

A9

Through actual on-site tests, it is found that the invention can significantly help improve the coplanarity of the ball grid array implanted on the back side of the substrate by providing an unwarped substrate. One example of the test data is shown in the following table (the data represent the measured distance between the ball grid array and reference plane).

IN THE ABSTRACT

Please amend the abstract as follows:

A10

A substrate strip with warpage-preventive linkage structure is proposed for a BGA (Ball Grid Array) application. The proposed substrate strip is composed of a series of substrates, each being used for the construction of an individual unit of a BGA package, and which is